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Ichihara-shi, Chiba 2990108 (JP). **TOGASHI, Atsushi**
[JP/JP]; c/o Dow Corning Toray Silicone Co., Ltd., 2-2,
Chigusa-kaigan, Ichihara-shi, Chiba 2990108 (JP).

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(71) Applicant (*for all designated States except US*): **DOW
CORNING TORAY SILICONE CO., LTD.** [JP/JP]; 1-3,
Marunouchi 1-chome, Chiyoda-ku, Tokyo 1000005 (JP).

(72) Inventors; and

(75) Inventors/Applicants (*for US only*): **MORITA, Yoshit-
sugu** [JP/JP]; c/o Dow Corning Toray Silicone Co., Ltd.,
2-2, Chigusa-kaigan, Ichihara-shi, Chiba 2990108 (JP).
ISSHIKI, Minoru [JP/JP]; c/o Dow Corning Toray
Silicone Co., Ltd., 2-2, Chigusa-kaigan, Ichihara-shi,
Chiba 2990108 (JP). **UEKI, Hiroshi** [JP/JP]; c/o Dow
Corning Toray Silicone Co., Ltd., 2-2, Chigusa-kaigan,

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(54) Title: CURABLE SILICONE COMPOSITION AND CURED PRODUCT THEREOF

(57) Abstract: A curable silicone composition includes: (A) an organopolysiloxane represented by the siloxane unit formula (1) given below and having at least two univalent organic groups that contain epoxy groups and are free of aromatic rings: $[R^1_3SiO_{1/2}]_a [R^2_2SiO_{2/2}]_b [R^3SiO_{3/2}]_c$ (where R^1 , R^2 , and R^3 are univalent organic groups, at least two of which are univalent organic groups which contain epoxy groups and are free of aromatic rings; more than 20 mole % of R^3 are aryl groups; $a + b + c = 1$; on average, "a" satisfies the following condition: $0 \leq a \leq 0.8$; on average, "b" satisfies the following condition: $0 \leq b \leq 0.8$; and, on average, "c" satisfies the following condition: $0.2 \leq c \leq 1.0$); (B) a linear-chain organopolysiloxane having at least two univalent organic groups that contain phenolic hydroxyl groups; and (C) a curing accelerator.

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